MP5010S

5V, 1A- 5A Programmable Current Limit Switch

The Future of Analog IC Technology

DESCRIPTION

The MP5010S is a protection device designed to protect circuitry on the output (source) from transients on input (V_{CC}). It also protects V_{CC} from undesired shorts and transients coming from the source.

At start up, inrush current is limited by limiting the slew rate at the source. The slew rate is controlled by a small capacitor at the dv/dt pin. The dv/dt pin has an internal circuit that allows the customer to float this pin (no connect) and still receive 1.1ms ramp time at the source.

The maximum load at the output (source) is current limited. This is accomplished by utilizing a sense FET topology. The magnitude of the current limit is controlled by an external resistor from the I-Limit pin to the Source pin.

An internal charge pump drives the gate of the power device, allowing a very low on-resistance DMOS power FET of just 40mΩ.

The source is protected from the V_{CC} input being too low or too high. Under Voltage Lockout (UVLO) assures that V_{CC} is above the minimum operating threshold, before the power device is turned on. If V_{CC} goes above the high output threshold, the source voltage will be limited.

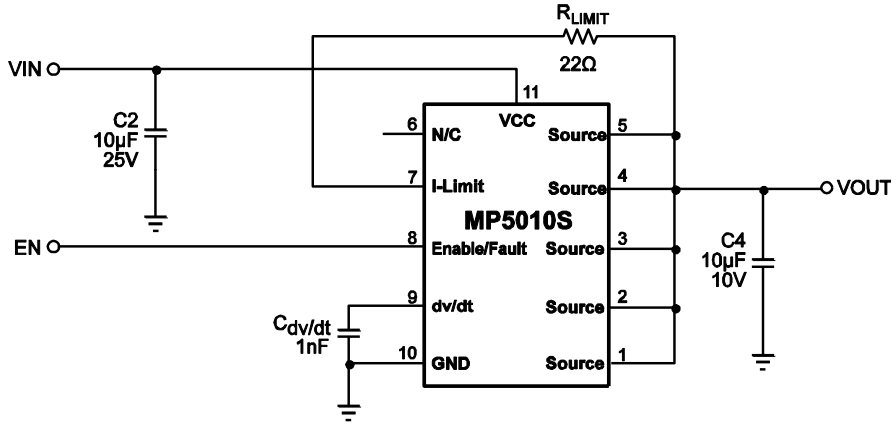
FEATURES

- Wide 3.6V-to-18V Operating Input Range
- Integrated 40mΩ Power FET
- Enable/Fault Pin
- Adjustable Slew Rate for Output Voltage
- Adjustable Current Limit
- Thermal Protection

APPLICATIONS

- Hot Swap
- Wireless Modem Data Cards
- PC Cards
- Laptops

TYPICAL APPLICATION

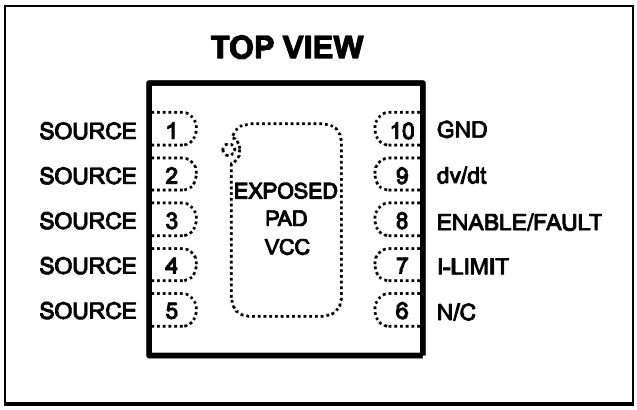


ORDERING INFORMATION

Part Number*	Package	Top Marking
MP5010SDQ	QFN10 (3mmx3mm)	AGK

***** For Tape & Reel, add suffix –Z (e.g. MP5010SDQ–Z).
For RoHS compliant packaging, add suffix –LF (e.g. MP5010SDQ-LF-Z).

PACKAGE REFERENCE



ABSOLUTE MAXIMUM RATINGS (1)

V_{CC}, SOURCE, I-LIMIT ..... –0.3V to 22V
dv/dt, ENABLE/FAULT..... –0.3V to 6V
Storage Temperature..... –65°C to +155°C
Junction Temperature .....+150°C
Lead Temperature .....+260°C
Continuous Power Dissipation (T_A=+25°C) (2)
……2.5W

Recommended Operating Conditions (3)

Input Voltage Operating Range..... 4V to 18V
Continuous Current
0.5 in^2 pad, T_A=25°C 4.2A
For Minimum Copper, T_A=80°C 2.3A
Operating Junction Temp. (T_J)..... -40°C to +125°C

Thermal Resistance (4) θ_{JA} θ_{JC}

QFN10 (3mmx3mm).....50 .....12 ...°C/W

Notes:

1) Exceeding these ratings may damage the device.
2) The maximum allowable power dissipation is a function of the maximum junction temperature T_J(MAX), the junction-to-ambient thermal resistance θ_{JA}, and the ambient temperature T_A, the maximum allowable power dissipation at any ambient temperature is calculated using: $P_D(MAX)=(T_J(MAX)-T_A)/\theta_{JA}$. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
   Reduce 0.2 Watts for every 10°C ambient temperature increasing
3) The device is not guaranteed to function outside of its operating conditions.
4) Measured on JESD51-7 4-layer board.

ELECTRICAL CHARACTERISTICS

V_{CC} = 5V, R_{LIMIT}=22Ω, Capacitive Load= 10μF, T_A=25°C, unless otherwise noted.

Parameters	Symbol	Condition	Min	Typ	Max	Units
Power FET						
Delay Time (5)	t_{DLY}	Enabling of chip to I_D=40mA with a 5Ω resistive load		0.2		ms
ON Resistance	R_{DSon}	T_J=25°C		40	55	mΩ
		T_J=85°C(6)		52		
Off State Output Voltage	V_{OFF}	V_{CC}=18V, V_{EN}=0V, R_L=500Ω			120	mV
Thermal Latch						
Shutdown Temperature (6)	T_{SD}			175		°C
Under/Over Voltage Protection						
Output Clamping Voltage	V_{CLAMP}	Overvoltage Protection V_{CC}=8V	5.95	6.65	7.35	V
Under Voltage Lockout	V_{UVLO}	Rising Edge	3.2	3.6	4.0	V
Under Voltage Lockout (UVLO) Hysteresis	V_{HYST}			0.4		V
Current Limit (7)						
Hold Current	I_{LIM-SS}	0Ω Short Resistance, R_{LIM}=22Ω	1.2	2	2.8	A
Trip Current	I_{LIM-OL}	R_{LIM}=22Ω		3.1		A
dv/dt Circuit						
Rise Time (8)	T_r	Float dv/dt pin	0.4	1.1	2.6	ms
Enable/Fault						
Low Level Input Voltage	V_{IL}	Output Disabled			0.5	V
Intermediate Level Input Voltage	$V_{I\ (INT)}$	Thermal Fault, Output Disabled	0.82	1.4	1.95	V
High Level Input Voltage	V_{IH}	Output Enabled	2.5			V
High State Maximum Voltage	$V_{I\ (MAX)}$			4.95		V
Pull Up Current (Source)	I_{IL}	V_{ENABLE}=0V	15	25	35	μA
Maximum Fanout for Fault Signal		Total number of chips that can be connected for simultaneous shutdown			3	Units
Maximum Voltage on Enable Pin(9)	V_{MAX}				VCC	V
Total Device						
Bias Current	I_{BIAS}	Device Operational		815	900	μA
		Thermal Shutdown		580	650	
Minimum Operating Voltage for UVLO	V_{MIN}	Enable<0.5V			2.5	V

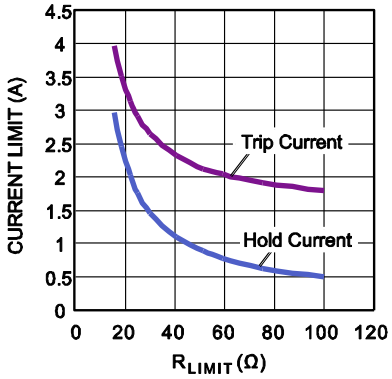
Notes:

5) Related to Rise Time. See description in Fault and Enable Pin Section on Page 9.
6) Guaranteed by design.
7) Guaranteed by Characterization Test.
8) Measured from 10% to 90%.
9) Maximum Input Voltage on Enable pin to be ≤6V if V_{CC} ≥ 6V. Maximum Input Voltage on Enable pin to be V_{CC} if V_{CC} ≤ 6V.

TYPICAL PERFORMANCE CHARACTERISTICS

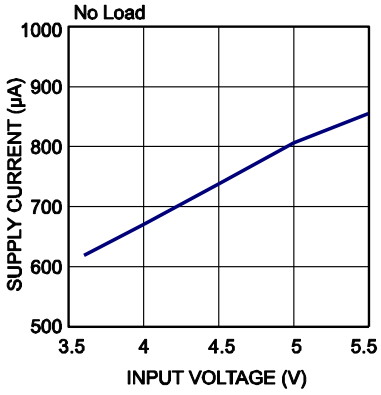
V_{IN} = 5V, V_{EN}=5V, R_{LIMIT}=22Ω, C_{OUT}=10μF, Cdv/dt =0nF, T_A=25°C, unless otherwise noted.

Trip Current & Hold Current vs. Rlimit



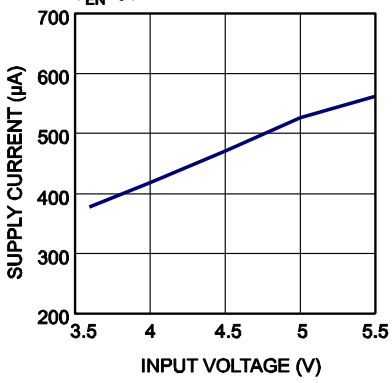
Supply Current, Output Enabled vs. Input Voltage

No Load



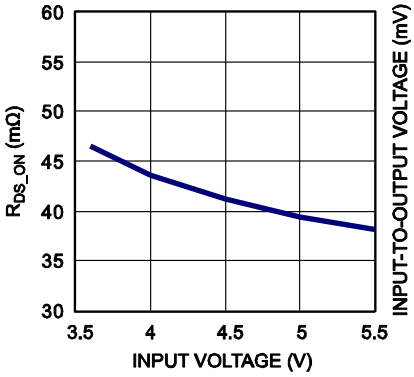
Supply Current, Output Disabled vs. Input Voltage

V_{EN}=0V

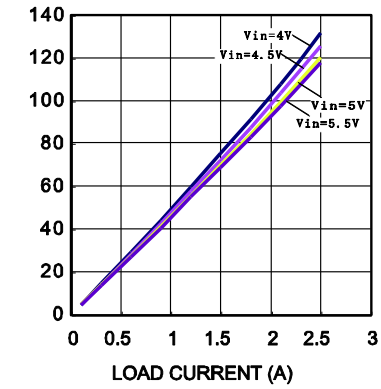


R_{DS_ON} vs. Input Voltage

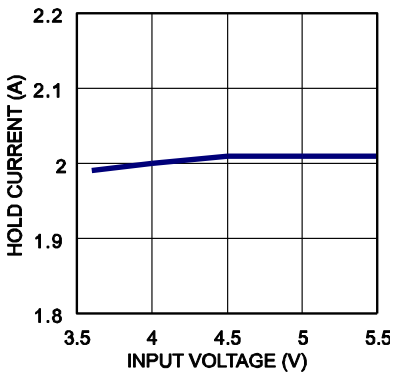
I_{OUT}=0.5A



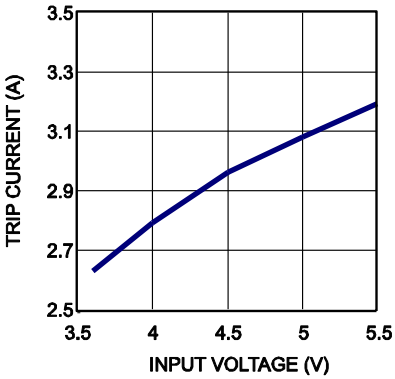
Input-to-output Voltage vs. Load Current



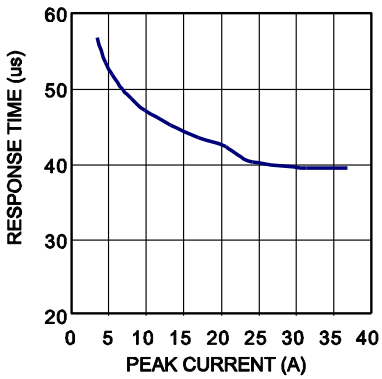
Hold Current vs. Input Voltage



Trip Current vs. Input Voltage



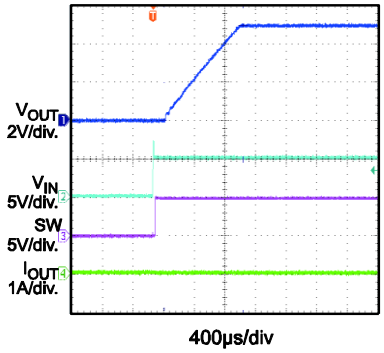
Current Limit Response vs. Peak Current



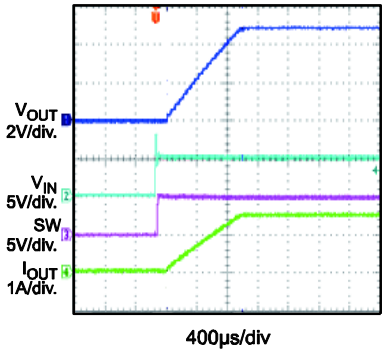
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{EN}=5V, R_{LIMIT}=22Ω, C_{OUT}=10µF, Cdv/dt =0nF, T_A=25°C, unless otherwise noted.

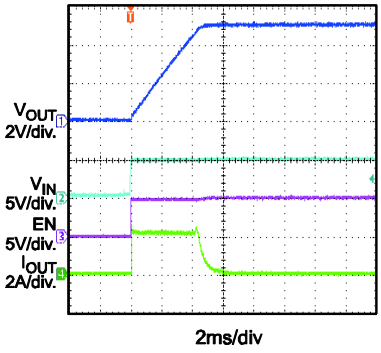
Startup through Input Voltage
En Float, No Load



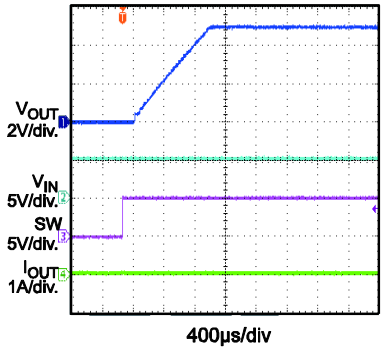
Startup through Input Voltage
En Float, R_{LOAD} = 3.3Ω



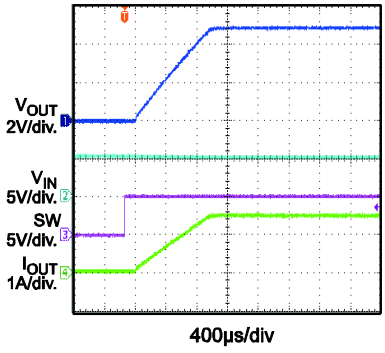
Startup through Input Voltage
En Float, No Load, C_{OUT} = 2200µF



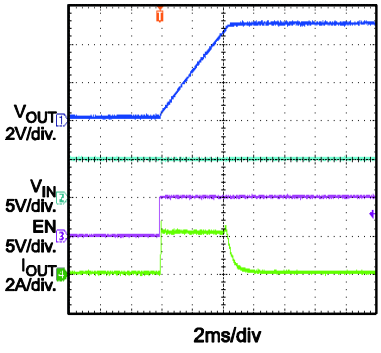
Startup through Enable
No Load



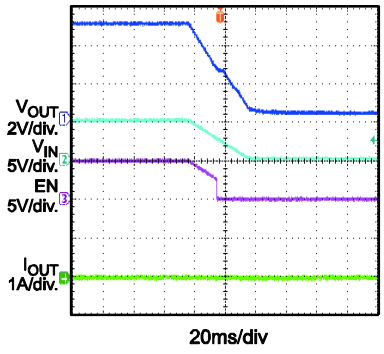
Startup through Enable
R_{LOAD} = 3.3Ω



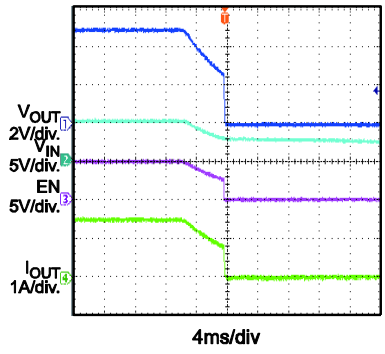
Startup through Enable
No Load, C_{OUT} = 2200µF



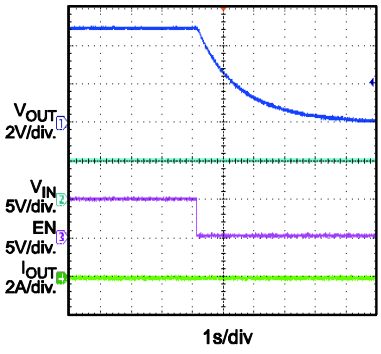
Shutdown through Input Voltage
No Load



Shutdown through Input Voltage
R_{LOAD} = 3.3Ω



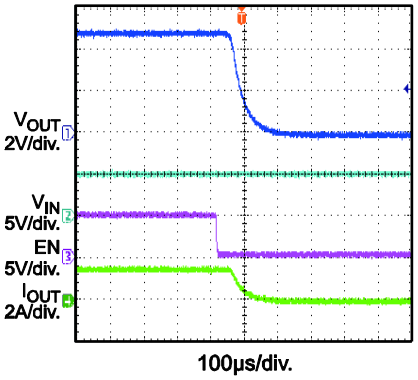
Shutdown through Enable
No Load



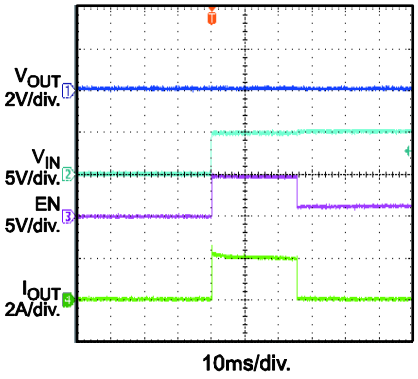
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, V_{EN}=5V, R_{LIMIT}=22Ω, C_{OUT}=10µF, Cdv/dt =0nF, T_A=25°C, unless otherwise noted.

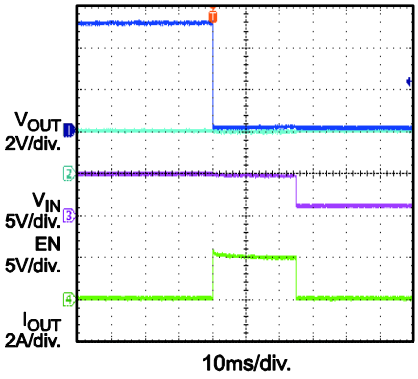
Shutdown Through Enable
R_{LOAD} = 3.3Ω



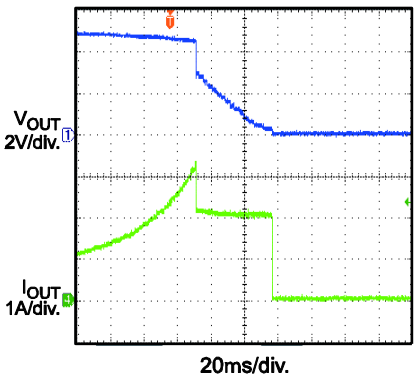
Short Circuit before Input Voltage Startup, and Thermal Shutdown



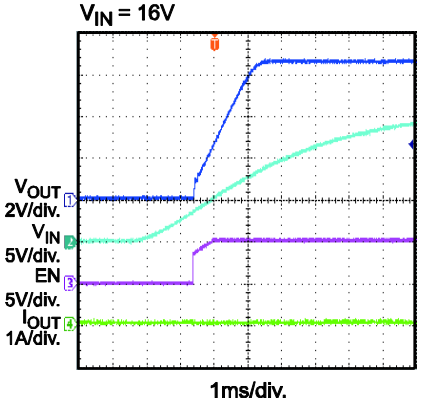
Short Circuit during Normal Operation, and Thermal Shutdown



Current Limit



Start Up into OVP, no load EN float
V_{IN} = 16V



PIN FUNCTIONS

Pin #	Name	Description
1-5	SOURCE	This pin is the source of the internal power FET and the output terminal of the IC.
6	N/C	DO NOT CONNECT, The pin must be float.
7	I-Limit	A resistor between this pin and the Source pin sets the overload and short circuit current limit levels.
8	Enable/Fault	The Enable/Fault pin is a tri-state, bi-directional interface. It can be used to enable the output of the device by floating the pin, or disable the chip by pulling it to ground (using an open drain or open collector device). If a thermal fault occurs, the voltage on this pin will go to an intermediate state to signal a monitoring circuit that the device is in thermal shutdown.
9	dv/dt	The internal dv/dt circuit controls the slew rate of the output voltage at turn on.
10	GND	Negative Input Voltage to the Device. This is used as the internal reference for the IC.
11 (Exposed Pad)	V_{CC}	Positive input voltage to the device.

BLOCK DIAGRAM

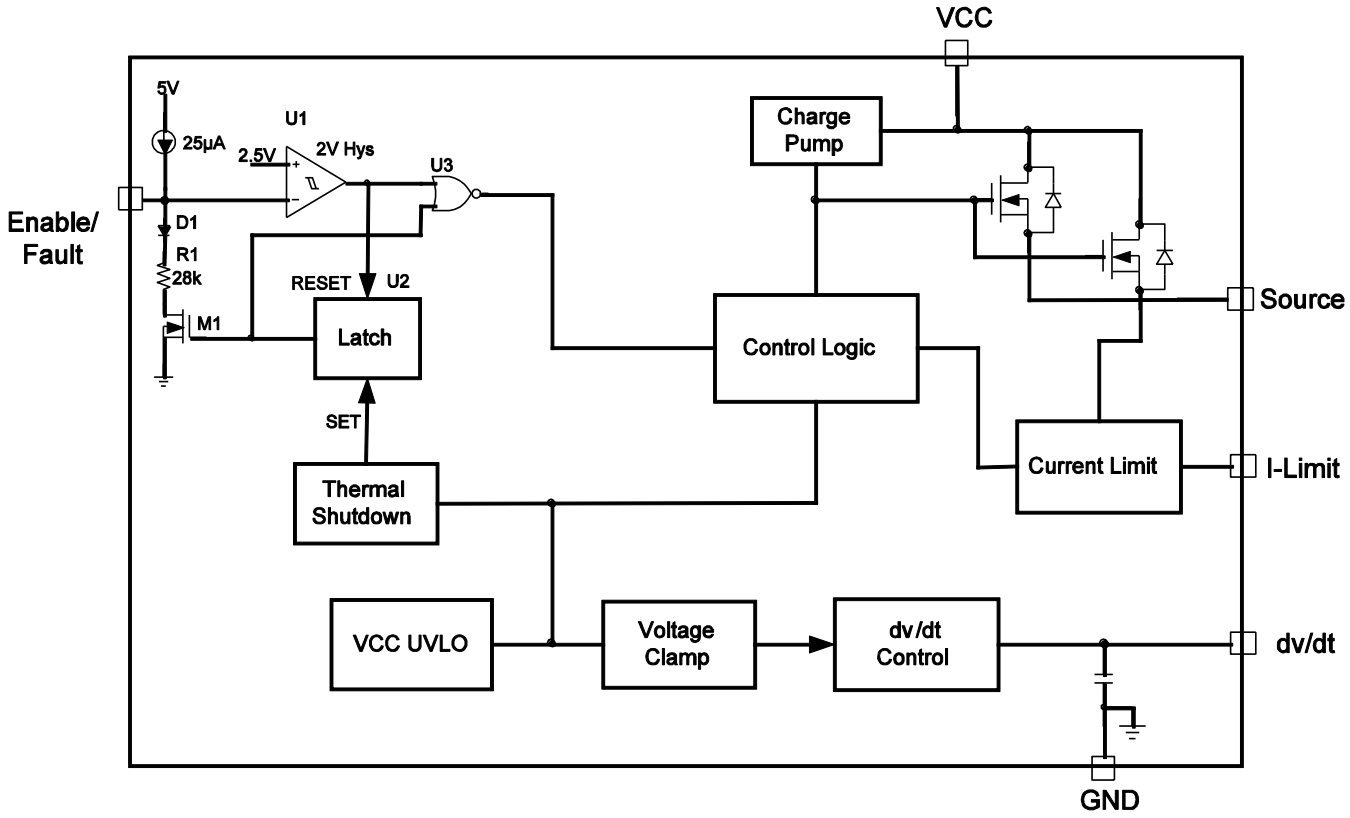


Figure 1—Functional Block Diagram

OPERATION

The MP5010S is designed to limit the in-rush current to the load when a circuit card inserts into a live backplane power source, thereby limiting the backplane's voltage drop and the dV/dt of the voltage to the load as well. It offers an integrated solution to monitor the input voltage, output voltage, output current and die temperature which eliminates the requirement of external current sense power resistor, power MOSFET and thermal sense device.

Under Voltage Lockout Operation

If the supply (input) is below the UVLO threshold, the output is disabled, and the EN/Fault line is driven low.

When the supply goes above the UVLO threshold, the output is enabled and the EN/Fault line is released. When the EN/Fault line is released it will be pulled high by a 25μA current source. No external pull up resistor is required. In addition, the pull up voltage is limited to 4.95 volts.

Output Over Voltage Protection

If the input voltage is higher than the OVP threshold, the output is clamped at 6.65V (typical) no matter what the output current is.

Current Limit

When the part is active, if load reaches trip current (minimum threshold current triggering over current protection) or a short is present, the part switches into to a constant-current (hold current) mode. Part will be shutdown only if the over current condition stays long enough to trigger thermal protection.

However, when the part is powered up by V_{CC} or EN, the load current should be smaller than hold current. Otherwise, the part can't be fully turned on.

In a typical application using a current limit resistor of 22Ω, the trip current will be 3.1A and the hold current will be 2A. If the device is in its normal operating state and passing 1.5A it will need to dissipate only 90mW with the very low on resistance of 40mΩ. For the package dissipation of 50°C/Watt, the temperature rise will only be + 9°C. Combined with a 25°C ambient, this is only 34°C total package temperature.

During a short circuit condition, the device now has 5V across it with constant hold current and therefore must dissipate large power. At 50°C/watt, if uncontrolled, the temperature would rise above the MP5010S thermal protection (+175°C) and shutdown the device to cause the temperature to drop below a hysteresis level. Proper heat sink must be used if the device is intended to supply the hold current and not shutdown. Without a heat sink, hold current should be maintained below 600mA at + 25°C and below 360mA at +85°C to prevent the device from activating the thermal shutdown feature.

Thermal Protection

When thermal protection is triggered, the output is disabled and the EN/Fault line is driven to the mid level. The thermal fault condition is latched (meaning the fault flag is set), and the part will remain latched off until the fault (enable) line is brought low. Cycling the power below the UVLO threshold will also reset the fault flag.

Fault and Enable Pin

The Enable/Fault Pin is a Bi-Directional three levels I/O with a weak pull up current (25μA typical). The three levels are low, mid and high. It functions to enable/disable the part and to relay Fault information.

Enable pin as an input:

1. Low and mid disable the part.
2. Low, in addition to disabling the part, clears the fault flag.
3. High enables the part (if the fault flag is clear) after a delay time. The delay time equation is as below:

$$T_{delay} = 80us + \frac{1}{6} t_{rise}$$

Enable pin as an output:

1. The pull up current may (if not over ridden) allow a "wired nor" pull up to enable the part.

2. An under voltage will cause a low on the enable pin, and will clear the fault flag.
3. A thermal fault will cause a mid level on the enable pin, and will set the fault flag

The Enable/Fault line must be above the mid level for the output to be turned on.

The fault flag is an internal flip-flop that can be set or reset under various conditions:

1. Thermal Shutdown: set fault flag
2. Under Voltage: reset fault flag
3. Low voltage on Enable/Fault pin: reset fault flag
4. Mid voltage on Enable/Fault pin: no effect

Under a fault, the Enable/Fault pin is driven to the mid level.

There are 4 types of faults, and each fault has a direct and indirect effect on the Enable/Fault pin and the internal fault flag. In a typical application there are one or more of the MP5010S chips in a system. The Enable/Fault lines will typically be connected together.

Table 1—Fault Function Influence in Application

Fault description	Internal action	Effect on Fault Pin	Effect on Flag	Effect on secondary Part
Short/over current	Limit current	none	none	none
Under Voltage	Output is turned off	Internally drives Enable/Fault pin to Logic low	Flag is reset	Secondary part output is disabled, and fault flag is reset.
Over Voltage	Limit output voltage	None	None	None
Thermal Shutdown	Shutdown part. The part is latched off until a UVLO or externally driven to ground.	Internally drives Enable/Fault pin to mid level	Flag is Set	Secondary part output is disabled.

APPLICATION INFORMATION

Current Limit Setting

The desired current limit is a function of the external current limit resistor.

Table 2—Current Limit vs. Current Limit Resistor (V_{CC}=5V)

R_{LIMIT} (Ω)	15.4	22	51	100
Trip Current (A)	4	3.1	2.1	1.8
Hold Current (A)	3	2	0.9	0.5

Rise Time Setting

The rise time is a function of the capacitor (Cdv/dt) on the dv/dt pin.

Table 3—Rise Time vs. Cdv/dt

Cdv/dt	none	50pF	500pF	1nF
Rise Time (TYPICAL)(ms)	1.1	2.2	12.3	23.5

* **Notes:** Rise Time = K_{RT}*(50pF+$C_{dv/dt}$), K_{RT} =22E6

The “rise time” is measured by from 10% to 90% of output voltage.

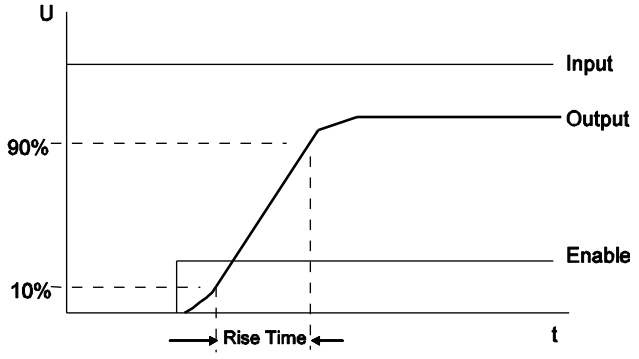
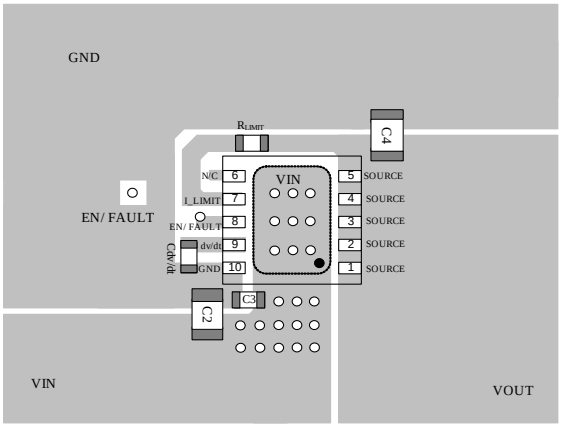


Figure 2—Rise Time

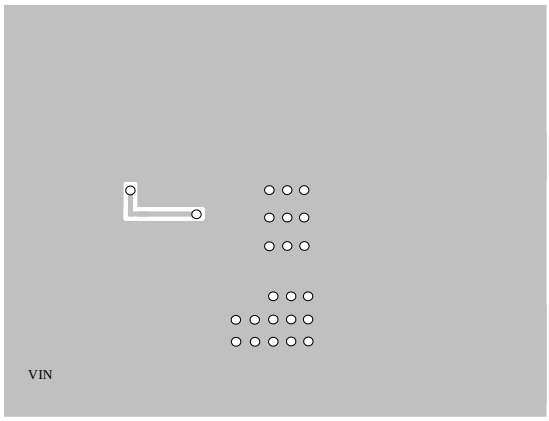
PCB Layout

PCB layout is very important to achieve stable operation. Please follow these guidelines and take below figure for reference.

Place Rlimit close to I_limit pin, Cdv/dt close to dv/dt pin and input cap close to Vcc pin. Keep the N/C pin float. Put vias in thermal pad and ensure enough copper area near Vcc and source to achieve better thermal performance.



Top Layer



Bottom Layer

Figure 3—PCB Layout

Design Example

Below is a direct current sensing design example following the application guidelines for the specifications:

Table 4—Design Example

V_{IN}	5V
Trip Current	3.1A
Hold Current	2A

The detailed application schematic is shown in Figure 4. The typical performance and circuit waveforms have been shown in the Typical Performance Characteristics section. For more device applications, please refer to the related Evaluation Board Datasheets.

TYPICAL APPLICATION CIRCUITS

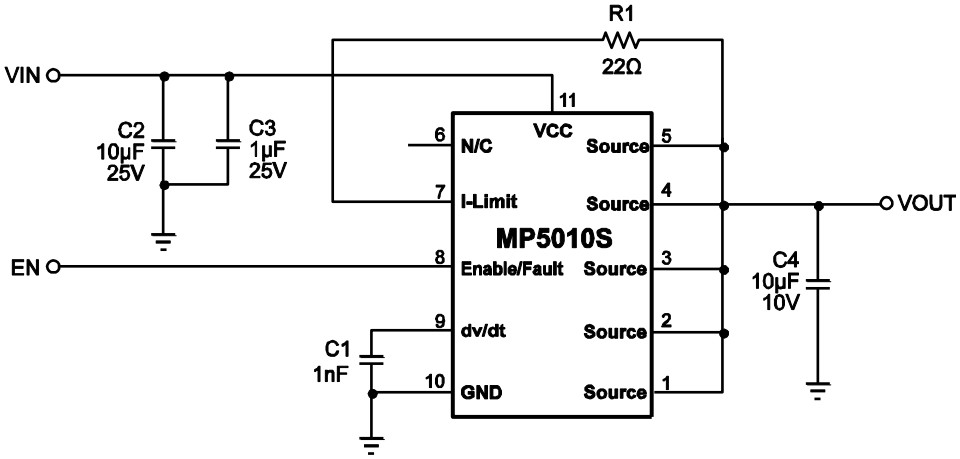
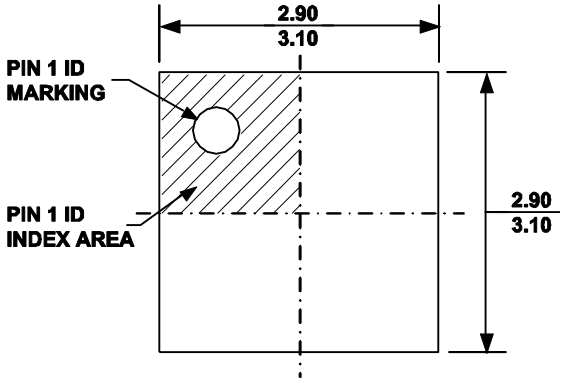


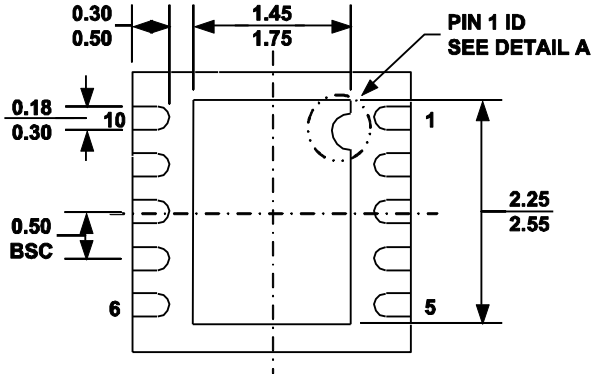
Figure 4—Application Circuit with Direct Current Sensing

PACKAGE INFORMATION

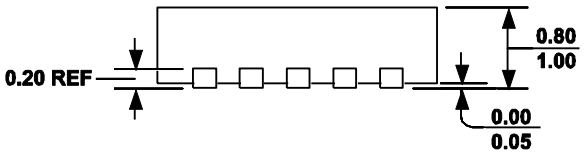
QFN10 (3mm x 3mm)



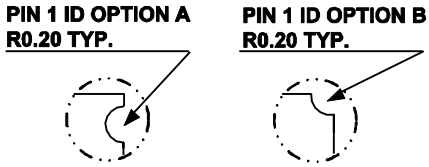
TOP VIEW



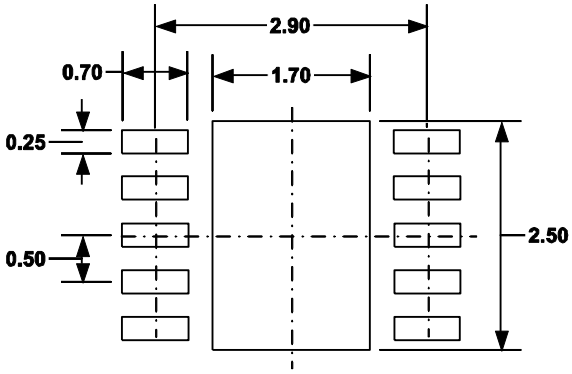
BOTTOM VIEW



SIDE VIEW



DETAIL A



RECOMMENDED LAND PATTERN

NOTE:

1) ALL DIMENSIONS ARE IN MILLIMETERS.
2) EXPOSED PADDLE SIZE DOES NOT INCLUDE MOLD FLASH.
3) LEAD COPLANARITY SHALL BE 0.10 MILLIMETER MAX.
4) DRAWING CONFORMS TO JEDEC MO-229, VARIATION VEED-5.
5) DRAWING IS NOT TO SCALE.

OCEAN CHIPS
Океан Электроники
Поставка электронных компонентов

Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «**JONHON**», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «**FORSTAR**».

AVIC JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).

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